

# Orbotech Corus™ 8M

Double-sided Imaging. Maximum Performance.



Orbotech Corus 8M is a fully automated direct imaging solution that replaces a complete DI line. Designed for Advanced HDI (including, mSAP) and IC substrate mass production, this integrated solution enables super-fine lines and outstanding accuracy, creating new opportunities for PCB manufacturers and designers.

Orbotech Corus leverages new and field-proven technologies for exceptionally high capacity and yield. This smart solution is compact, closed and clean, guaranteeing cutting-edge performance and eco-friendly manufacturing.



GO GREEN

## Benefits

### Fully Integrated Inline Solution

- Fully automated, double-sided imaging solution that replaces a complete DI line
- Unique optics and an ultra-powerful, multi-wave laser system for extremely high speed imaging
- Innovative panel handling and cleanliness mechanisms

### Outstanding Resolution and Accuracy

- Super-fine, highly uniform line structure
- Exceptional positioning accuracy enabled by high precision design and advanced scaling algorithms
- High depth-of-focus (DOF) for best line quality on varying surface topographies

### Smart Operation

- High-speed, multi-target acquisition for any layout, ensuring high productivity
- Intelligent job queue management to streamline workflow processes
- Supports Industry 4.0 for advanced traceability and process optimization

### Reduced TCO

- High throughput achieved by a combination of large scan optics, on-the-fly target recognition and efficient automation
- Small footprint for maximum capacity per m<sup>2</sup>, occupying less clean room
- Highly efficient power consumption

## Technologies



**DSI™ Technology**

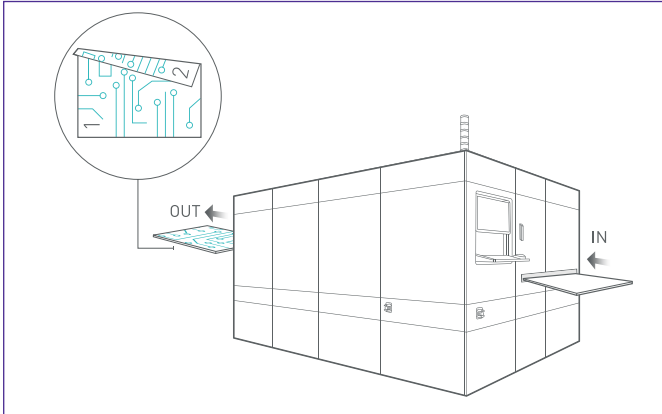


**LSO™ Technology**



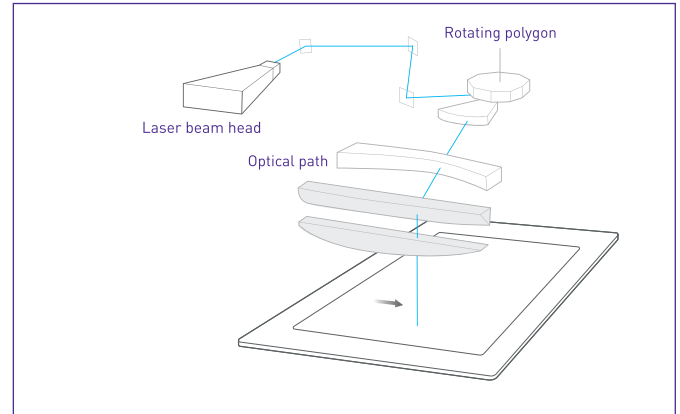
**MultiWave Laser™ Technology**

## Fully Automated, Double-Sided DI



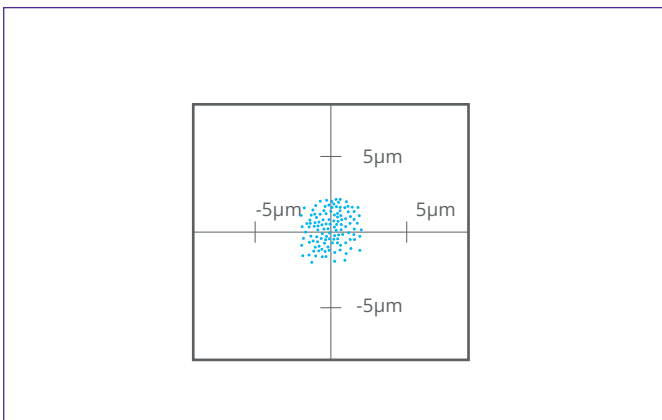
Fully automated, double-sided DI solution to maximize capacity and yield for high-volume production

## Superior Line Quality



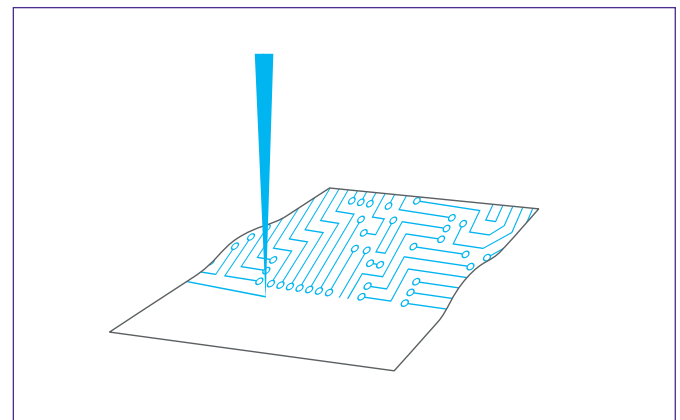
Super-fine line structure in a single scan enabled by KLA's field-proven LSO™ Technology

## Outstanding Accuracy



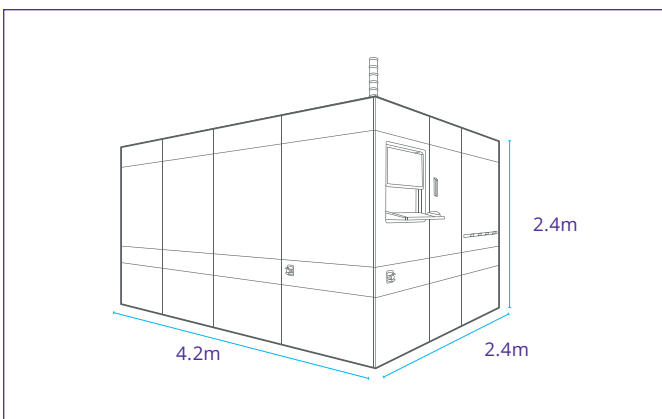
Registration accuracy as fine as  $\pm 5\mu\text{m}$  for advanced applications

## High Depth-of-Focus (DOF)



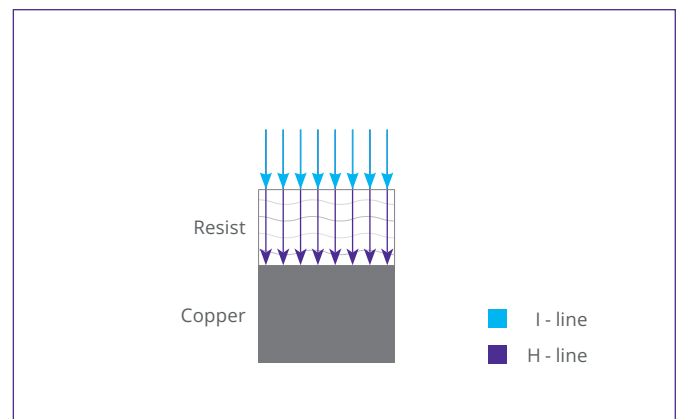
High depth-of-focus (DOF) for best line precision and uniformity on varying surface topographies

## All-in-one, Compact Design



Fully integrated solution in a closed, compact box for maximum cleanliness and efficiency

## Maximum Resist Flexibility



Compatible with a wide range of resists and processes, driven by KLA's field-proven MultiWave Laser™ technology

## Specifications

### Orbotech Corus 8M

Minimum Line Width*	8μm
Minimum Pitch*	20μm
Edge Roughness, 3σ	±1μm
Registration Accuracy (FTG), 3σ**	±5μm
Registration Accuracy (FTB), 3σ**	10μm
Maximum Substrate Size	660mm x 660mm (26" x 26")
Maximum Exposure Size	635mm x 660mm (25" x 26")
Dimensions (l) x (w) x (h)	4.2m x 2.4m x 2.4m

\* Dependent on resist type and processes

\*\* Accuracy is based on 4 target registration

Orbotech Corus includes Laser Class 1 product according to IEC 60825-1:2022

#### KLA SERVICES

From tool installation and system optimization to productivity enhancements and global supply chain management, KLA Services is a trusted partner to customers around the world — delivering an unrivaled experience focused on maximizing tool performance and availability.

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